

500mW High Speed Switching Diode

FEATURES

- Fast switching device (trr<4.0ns)
- Through-hole device type mounting
- Moisture sensitivity level 1
- Solder hot dip Tin(Sn) lead finish
- Pb free version and RoHS compliant
- All external surfaces are corrosion resistant and leads are readily solderable
- Packing code with suffix "G" means Halogen-free







DO-35 Hermetically Sealed Glass

MECHANICAL DATA

- Case : DO-35
- High temperature soldering guaranteed: 260°C/10s
- Polarity: Indicated by black cathode band
- Weight : 109 ± 4 mg

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)						
PARAMETER	SYMBOL	VALUE	UNIT			
Power Dissipation	P _D	500	mW			
Repetitive Peak Reverse Voltage	V _{RRM}	100	V			
Peak Forward Surge Current Pluse Width = 1µs, Square Wave	I _{FSM}	2.0	А			
Non-Repetitive Peak Forward Current	I _{FM}	450	mA			
Average Forward Current	I _O	150	mA			
Thermal Resistance (Junction to Ambient)	R _{θJA}	240	°C/W			
Junction and Storage Temperature Range	T _J , T _{STG}	-65 to +150	۵°			

PARAMETER	SYMBOL	MIN	ΤΥΡ	MAX	CONDITION	UNIT
Reverse Breakdown Voltage	V _(BR) 100 75	100	-	-	Ι _R =100μΑ	V
Reverse breakdown voltage		Ι _R =5μΑ	v			
		0.62	-	0.72	1N4448 , 1N914B I _F =5.0mA	
Forward Voltage	V_{F}	-	-	1.0	1N4148 I _F =10.0mA	V
		-	-	1.0	1N4448, 1N914B I _F =100.0m	
Reverse Leakage Current	I _R	-	-	25	V _R =20V	nA
Reverse Leakage Guilent		-	-	5.0	V _R =75V	μA
Junction Capacitance	CJ	-	-	4.0	V _R =0 , f=1.0MHz	рF
Reverse Recovery Time (Note 1)	Trr	-	-	4.0		ns

Note : 1. Test Conditions : I_F =10mA, V_R =6V, R_L =100 Ω , I_{RR} =1mA



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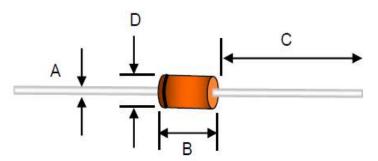
ORDERING INFORMATION							
PART NO.	PART NO. SUFFIX (Note 2)	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING		
1Nxxxx	-xx (2 (1)))-35	DO 35	10K / 14" Reel				
(Note1)		A0	6	DO-35	5K / Box (Ammo)		

Note 1: "xxxx" is device code from 1N4148 to 1N914B

Note 2: Part No. Suffix "-xx " would be used for special requirement

EXAMPLE						
PREFERRED PART NO.	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION	
1N4148 R0G	1N4148		R0	G	Multiple manufacture source Halogen free	
1N4148-L0 R0G	1N4148	LO	R0	G	Define manufacture source Halogen free	
1N4148-B0 R0G	1N4148	B0	R0	G	Define manufacture source Halogen free	

PACKAGE OUTLINE DIMENSION



DIM.	Unit	(mm)	Unit (inch)		
	Min	Мах	Min	Max	
А	0.34	0.60	0.013	0.024	
В	2.90	5.08	0.114	0.200	
С	25.40	38.10	1.000	1.500	
D	1.30	2.28	0.051	0.090	

MARKING DIAGRAM





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RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)

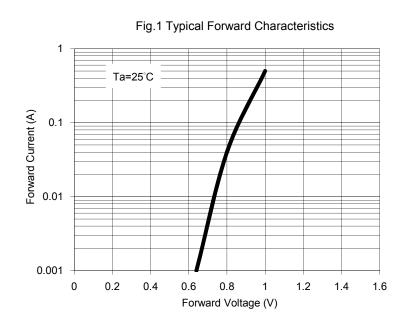


Fig. 3 Admissible Power Dissipation Curve

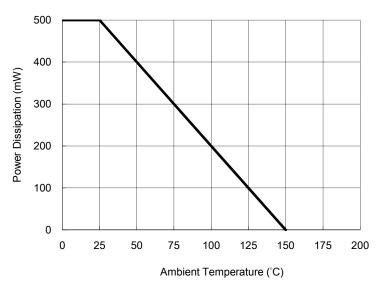
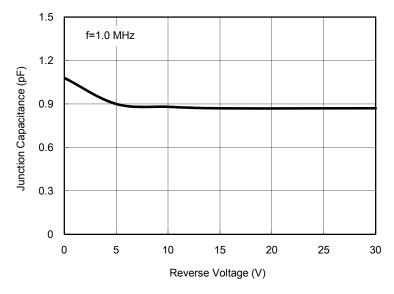


Fig. 2 Reverse Current VS. Reverse Voltage 10000 100°C 1000 Reverse Current : IR (nA) 70°C 100 50°C Ta=25°C 10 1 0 20 40 60 80 100 120 Reverse Voltage : VR (v)

Fig. 4 Typical Junction Capacitance





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